

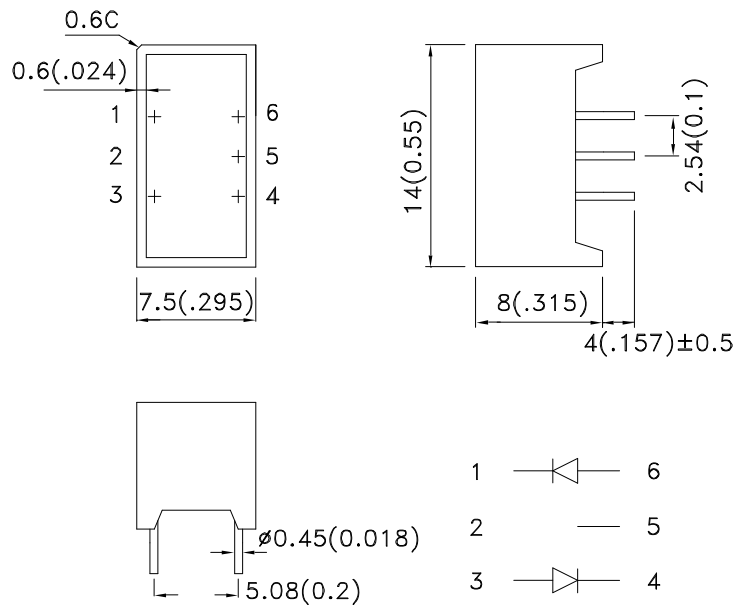
### Features

- UNIFORM LIGHT EMITTING AREA.
- EASILY MOUNTED ON P.C. BOARDS OR INDUSTRY STANDARD SOCKETS.
- FLUSH MOUNTABLE.
- EXCELLENT ON/OFF CONTRAST.
- CAN BE USED WITH PANELS AND LEGEND MOUNTS.
- MECHANICALLY RUGGED
- I.C. COMPATIBLE.
- RoHS COMPLIANT.

### Description

The High Efficiency Red source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Orange Light Emitting Diode.

### Package Dimensions & Internal Circuit Diagram



Notes:

1. All dimensions are in millimeters (inches). Tolerance is  $\pm 0.25(0.01)$  unless otherwise noted.
2. Specifications are subject to change without notice.



## Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [1] @ 10mA	
			Min.	Typ.
DE/2ID	High Efficiency Red (GaAsP/GaP)	RED DIFFUSED	8	31

Note:

1. Luminous intensity/ luminous Flux: +/-15%.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
$\lambda_{peak}$	Peak Wavelength	High Efficiency Red	627		nm	I <sub>F</sub> =20mA
$\lambda_D$ [1]	Dominant Wavelength	High Efficiency Red	625		nm	I <sub>F</sub> =20mA
$\Delta\lambda_{1/2}$	Spectral Line Half-width	High Efficiency Red	45		nm	I <sub>F</sub> =20mA
C	Capacitance	High Efficiency Red	15		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	High Efficiency Red	2.0	2.5	V	I <sub>F</sub> =20mA
I <sub>R</sub>	Reverse Current	High Efficiency Red		10	uA	V <sub>R</sub> =5V

Notes:

1. Wavelength: +/-1nm.

2. Forward Voltage: +/-0.1V.

## Absolute Maximum Ratings at TA=25°C

Parameter	High Efficiency Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	160	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	
Lead Solder Temperature[2]	260°C For 3-5 Seconds	

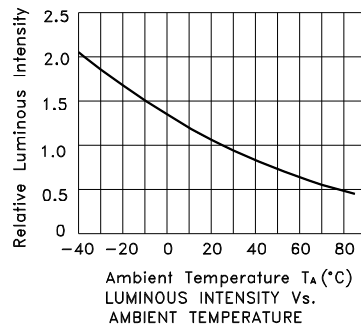
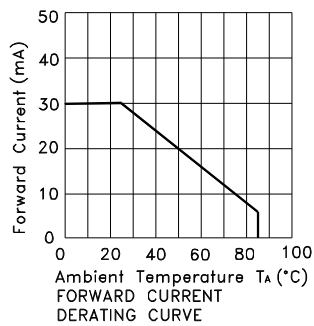
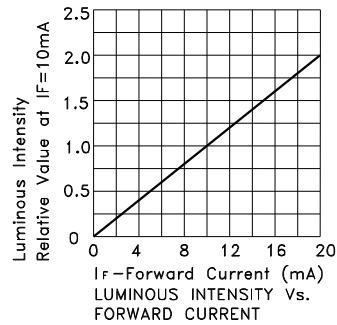
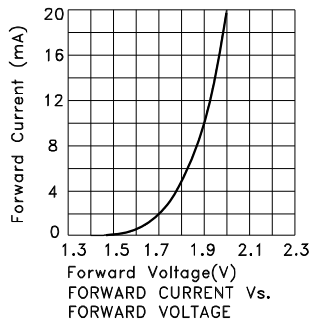
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

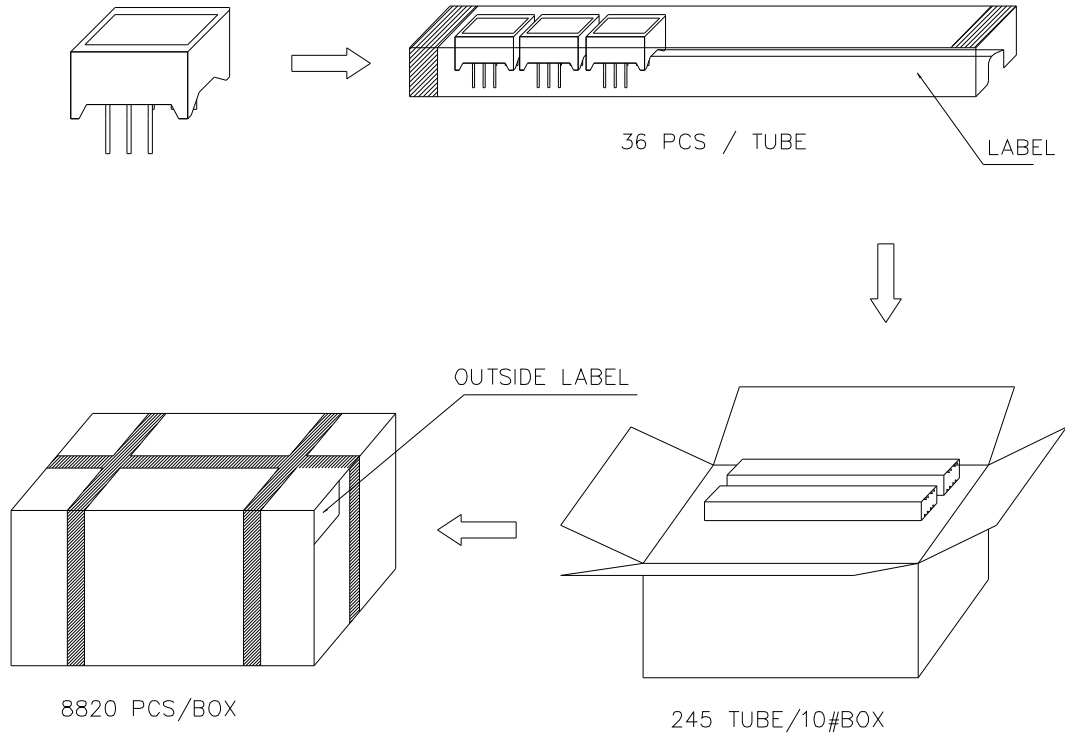


## High Efficiency Red DE/2ID

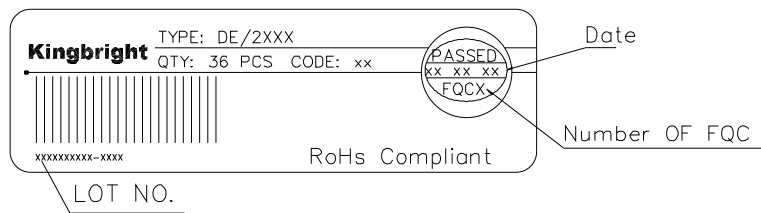


## PACKING & LABEL SPECIFICATIONS

## DE/2ID



Inside LABEL Paste On The IC-TUBE



Outside LABEL Paste On The Box

